

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	IPC100N04S5-1R2	**Issued**	08. April 2022
MA#	MA005709732		
Package	PG-TDSON-8-34	**Weight***	113.57 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.124	1.87	1.87	18703	18703
leadframe	inorganic material	phosphorus	7723-14-0	0.016	0.01		140	
	non noble metal	iron	7439-89-6	0.053	0.05		466	
	non noble metal	copper	7440-50-8	52.842	46.55	46.61	465276	465882
wire	noble metal	gold	7440-57-5	0.042	0.04	0.04	370	370
encapsulation	organic material	carbon black	1333-86-4	0.073	0.06		645	
	plastics	epoxy resin	-	5.785	5.09		50942	
	inorganic material	silicondioxide	60676-86-0	30.758	27.08	32.23	270829	322416
leadfinish	non noble metal	tin	7440-31-5	1.574	1.39	1.39	13857	13857
plating	noble metal	silver	7440-22-4	0.209	0.18	0.18	1842	1842
solder	non noble metal	tin	7440-31-5	0.046	0.04		404	
	noble metal	silver	7440-22-4	0.057	0.05		505	
	non noble metal	lead	7439-92-1	2.192	1.93	2.02	19304	20213
heat sink clip	inorganic material	phosphorus	7723-14-0	0.005			45	
	non noble metal	iron	7439-89-6	0.017	0.01		148	
	non noble metal	copper	7440-50-8	16.828	14.82	14.83	148168	148361
clip plating	noble metal	silver	7440-22-4	0.639	0.56	0.56	5626	5626
heatspreader	inorganic material	phosphorus	7723-14-0	0.000			1	
	non noble metal	iron	7439-89-6	0.000			3	
	non noble metal	copper	7440-50-8	0.310	0.27	0.27	2726	2730
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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